

AMENDMENTS TO THE SPECIFICATION

Please amend the specification, as follows:

Please replace page 5, lines 1 and 2 of the specification with the following amended paragraphs:

Fig. 4A is a bottom view of the high-frequency switching module according to the present invention;

Fig. 4B is an enlarged view of a portion of the bottom view of the high-frequency switching module shown in Fig. 4A;

Please replace page 6, lines 7 - 15 of the specification with the following amended paragraph:

The high-frequency switching module has a structure of a multi-layer assembly 1 formed of a dielectric material. The multi-layer assembly 1 is provided with circuit electrodes which are patterned (e.g., provided) inside thereof for serving as a switching circuit 3 and a filtering circuit 4 as shown in Fig. 2A (or fig. 2B). Also, circuit components 5 including diodes, capacitors, and inductors are mounted on the top side 101 of the multi-layer assembly 1 to form parts of the switching circuit 3 and filtering circuit

4.

Please replace page 10, line 24 - page 11, line 6 of the specification with the following amended paragraph:

Returning back to Fig. 3, the dielectric sheets 1a and 1c have grounding electrodes 20a and 20b provided respectively on substantially the entire surfaces thereof. The dielectric sheet 1f has a grounding electrode 20c provided on a right half of the surface thereof. The grounding electrodes 20a, 20b, and 20c are connected through via-holes (VH) respectively to the grounding terminals 19a shown in Fig. 4A.

Please replace page 11, line 22 - page 12, line 4 of the specification with the following amended paragraph:

On the dielectric sheet 1d, the coil electrode 24 and a strip line electrode 25a are provided, and the coil electrode 24 is connected at one end through a via-hole to the transmission terminal 6a shown in Fig. 4A, hence forming the coil 7 shown in Fig. 2. The strip line electrode 25a is connected at one end through a via-hole to the reception terminal 11a shown in Fig. 4A, thus forming a part of the strip line 14 shown in Fig 2.

Please replace page 15, lines 11-18 of the specification with the following amended paragraph:

As shown in Fig. 4A, the high-frequency terminals 2 including the antenna terminal 10a, transmission terminal 6a, and reception terminal 11a of the high-frequency switching module are provided on the bottom 102, i.e., mounting surface of the multi-layer assembly 1 onto a board of a high-frequency apparatus while the side surfaces 103 of the multi-layer assembly 1 shown in Fig. 1 are used as no-electrode provided sides.

Please replace page 20, line 24 - page 21, line 2 of the specification with the following amended paragraph:

Furthermore, in the arrangement of the high-frequency terminals 2, the high-frequency terminals 2 are spaced from the outer edge of the multi-layer assembly 1 (shown by spacings 6s, 19s and 11s in Fig. 4B) so that the strength against peeling off can be improved.

Please delete the paragraph found at page 27, lines 14 - 16 of the specification.